

HGP10000 Thermal Gap Pad

BENEFITS AND FEATURES

- 10 W/m-K thermal conductivity
- Ultra-high compressibility for low stress applications
- High residual stress after relaxation
- Excellent surface wetting for low contact resistance
- High reliability
- Electrically insulating

OVERVIEW

Honeywell HGP10000 thermal gap pad provides high thermal performance with ease of use across multitude of applications. Its ultra-high compressibility enables low stress and excellent conformity to mating surfaces. It is designed to minimize thermal resistance at interfaces, and maintain excellent performance through reliability testing.

Products are available in thickness range from 1mm to 5.0mm with 0.25mm incremental.

Thickness Tolerance: $\pm 10\%$

Please check thickness availability before order

TYPICAL APPLICATIONS

- Consumer electronics
- Telecommunications & network servers
- Automotive electronics
- Power devices & modules
- Semiconductors logics & memory

Storage & Use

- Shelf life 12 months at 0-35°C, <65%RH;

Property	Test Method	Unit	HGP10000
Color	Visual	-	Grey
Thermal Conductivity	ASTM D5470	(W/m-K)	10.0
Thermal Impedance	ASTM D5470 (1mm@10psi)	(°C-in ² /W)	0.16
Specific Gravity	ASTM D792	-	3.2
Hardness	ASTM D2240	Shore00	40
Thickness	ASTM D374	mm	1.0-5.0
Dielectric Constant@1MHz	ASTM D150		5.5
Volume Resistivity	ASTM D257	Ohm.cm	2.0X10 ¹³
Flammability Rate	UL94		V-0

Honeywell Electronic Materials

USA: 1-509-252-2102
 China: 400-840-2233
 Germany: 49-5137-999-9199
 Japan: 81-3-6730-7092
 Korea: 82-2-3483-5076
 Singapore: 65-6580-3593
www.electronicmaterials.com

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